



Advanced Product / Process Change Notice

No.: Z200-APCN-DM201504-01-Q

Date: 05/08/2015

Change Title : 2Gb (256Mb x8 and 128Mb x16) DDR2 technology migration from 65nm to 46nm

Change Classification: Major Minor

Change item : Design Raw Material Wafer FAB Package Assembly Testing Others

Affected Product(s) :

W972GG8JB-18 , W972GG8JB18A , W972GG8JB18I , W972GG8JB-25 , W972GG8JB25A , W972GG8JB25I , W972GG8JB25K , W972GG8JB-3 , W972GG8JB-3A , W972GG8JB-3I , W972GG8JB-3K , W972GG6JB-18 , W972GG6JB18A , W972GG6JB18I , W972GG6JB-25 , W972GG6JB25A , W972GG6JB25I , W972GG6JB25K , W972GG6JB-3 , W972GG6JB-3A , W972GG6JB-3I , W972GG6JB-3K

Description of Change(s) :

Technology migration (65nm to 46nm) for 2Gb DDR2.

Reason for Change(s) :

According to Winbond product roadmap , launch new 2Gb DDR2 with 46nm technology.

Impact of Change(s) : (positive & negative)

Form : No Change

Fit : No Concern (Package size x16 from 11X13 MM² (65nm) to 8X12.5 MM² (46nm) / x8 from 11X11.5 MM² (65nm) to 8X12.5 MM² (46nm)), Refer to attachment II in details)

Function : No Concern (Compatible between 65nm and 46nm)

Reliability : On-going

Hazardous Substances: No Concern (Please refer to attachment I)

Qualification Plan/ Results :

The new sample has passed ESD pass 2KV, latch-up pass 200mA and full qualification is in progress.

The result is expected out on June/22/2015.

Implementation Plan :

The follow-up disposition of 65nm 256Mb x8 and 128Mb x16 DDR2:

- 1) The date of Last-buy orders for the 65nm 256Mb x8 and 128Mb x16 DDR2: July. 31, 2015.
- 2) The last shipment date of the 65nm 256Mb x8 and 128Mb x16 DDR2: October, 30, 2015.

Date Code: _____ onward Lot No: _____ onward Proposed first ship date: 04/30/2015

Originator: (QA Sec. Manager)

Approval: (QA Dept. Manager)

Approval: (QRA Director)



**Contact for Questions
& Concerns**

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Customer Comments:

Note: Please sign this notice, and return to Winbond contact within 30 days. If no response is received within 30 days, this Change Request will be assumed to meet your approval.

Approval Disapproval Conditional Approval : _____.

Comment:

Date: _____

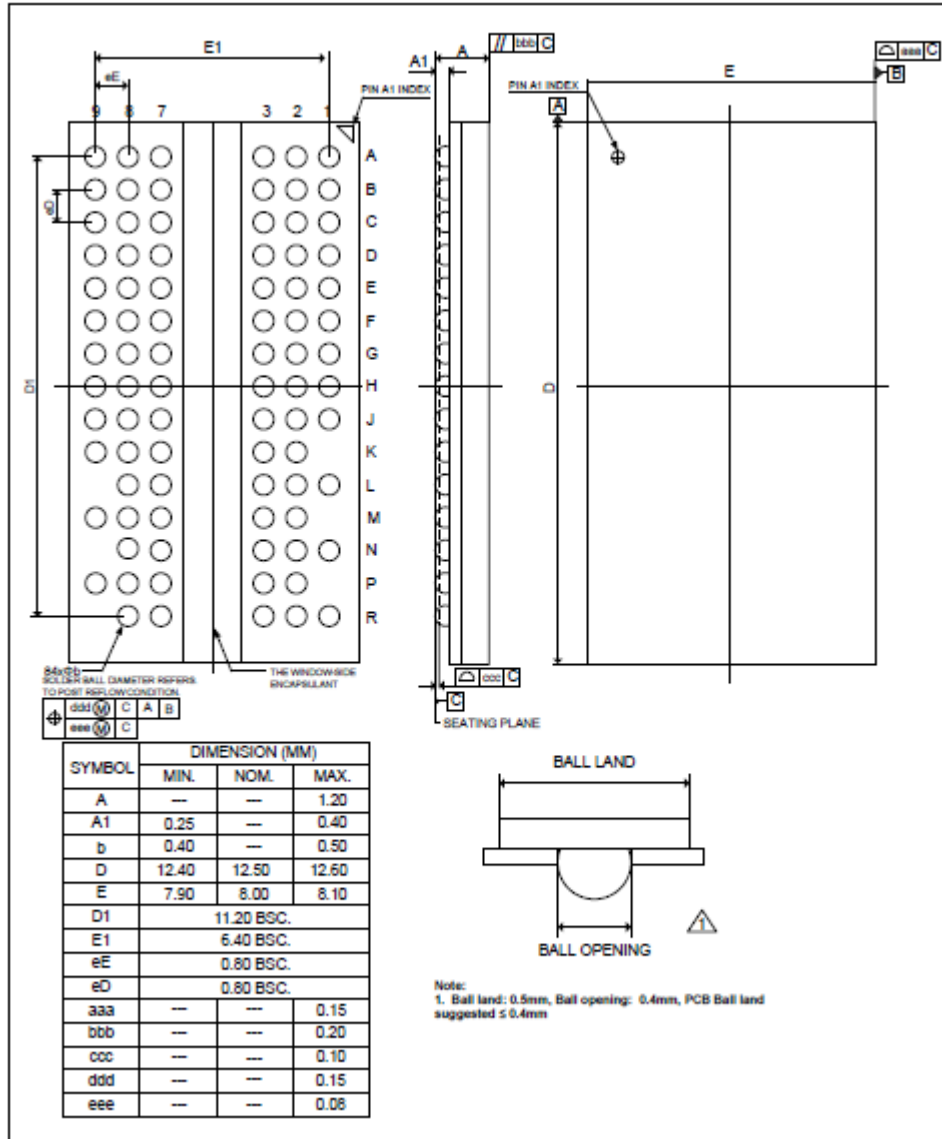
Dept. name: _____

Person in charge: _____

DDR2 46nm 128Mb x16 PACKAGE SPECIFICATION



Package Outline WBGA84 (8x12.5 mm², ball pitch: 0.8mm, Ø=0.45mm)



DDR2 46nm 256Mb x8 PACKAGE SPECIFICATION



Package Outline WBGA60 (8x12.5 mm², ball pitch: 0.8mm, Ø=0.45mm)

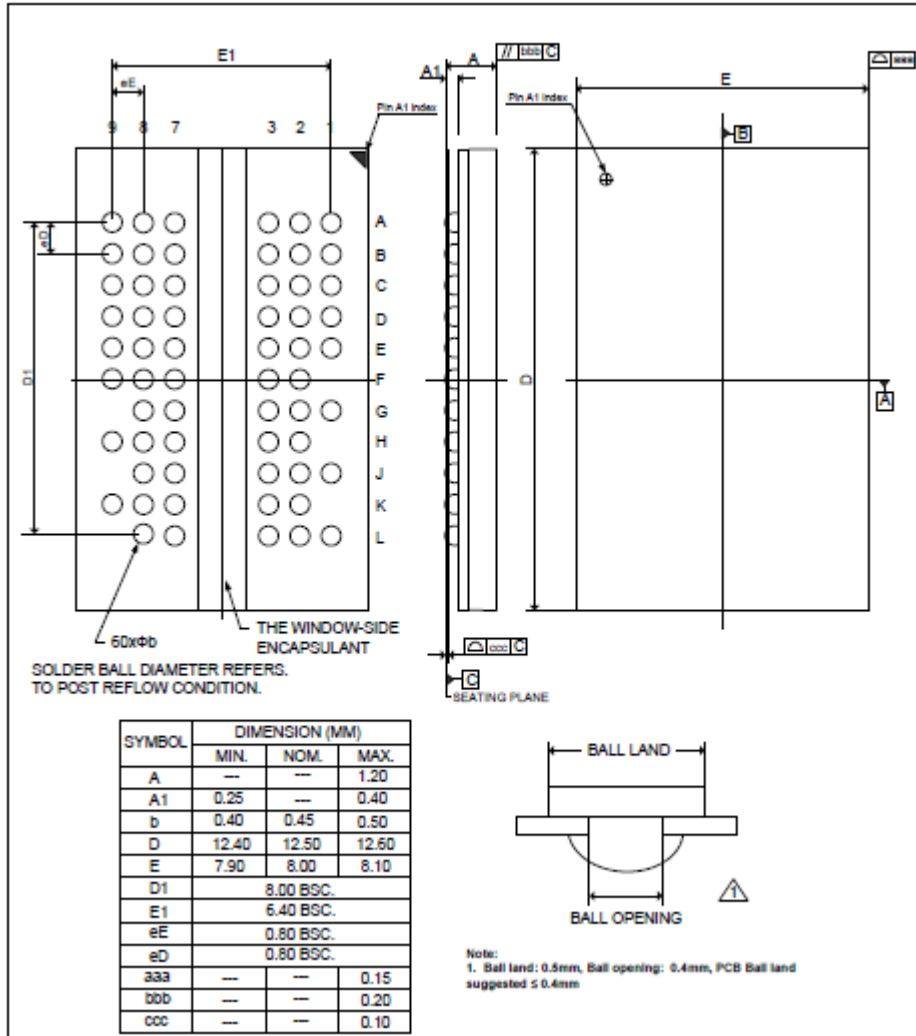




Table 1. The comparison table of part no between T65 and T46

Product	65nm Part No	46nm Part No
DDR2 256Mb x8	W972GG8JB	W972GG8KB
DDR2 128Mb x16	W972GG6JB	W972GG6KB